



3 pipe and H.D.T. Core



High Density AL Fin

Product Specification	
Application Socket	Intel LGA 2011(Narrow Type)
Cooler Dimension	107mm X 72.5mm X 64mm
Heat Sink Material	Heatpipe + AL Fin +AL Base
Fan Dimension	60X60X25
Bearing Type	2 BALL Bearing Fan Life Expectancy at 25°C 40000HR
Fan Speed (RPM)	2000~6500
Fan Airflow (CFM)	31.97 Max
Static Pressure (inchH2O)	0.4Max
Fan Noise Level (dBA)	<41
Rated Voltage (V)	12
Weight (g)	294
Application System	2U Form Factor Active Solution
CPU Support	Intel® Sandy Bridge Romley-EP/EX Narrow ILM Processors up to TDP 130 Watts



Features:

- Max TDP 130W
- 3XΦ6mm Heatpipe Provides Faster Heat Dissipation Rate
- Design For 2U Server
- PWM Function Fan for a Silent Operation